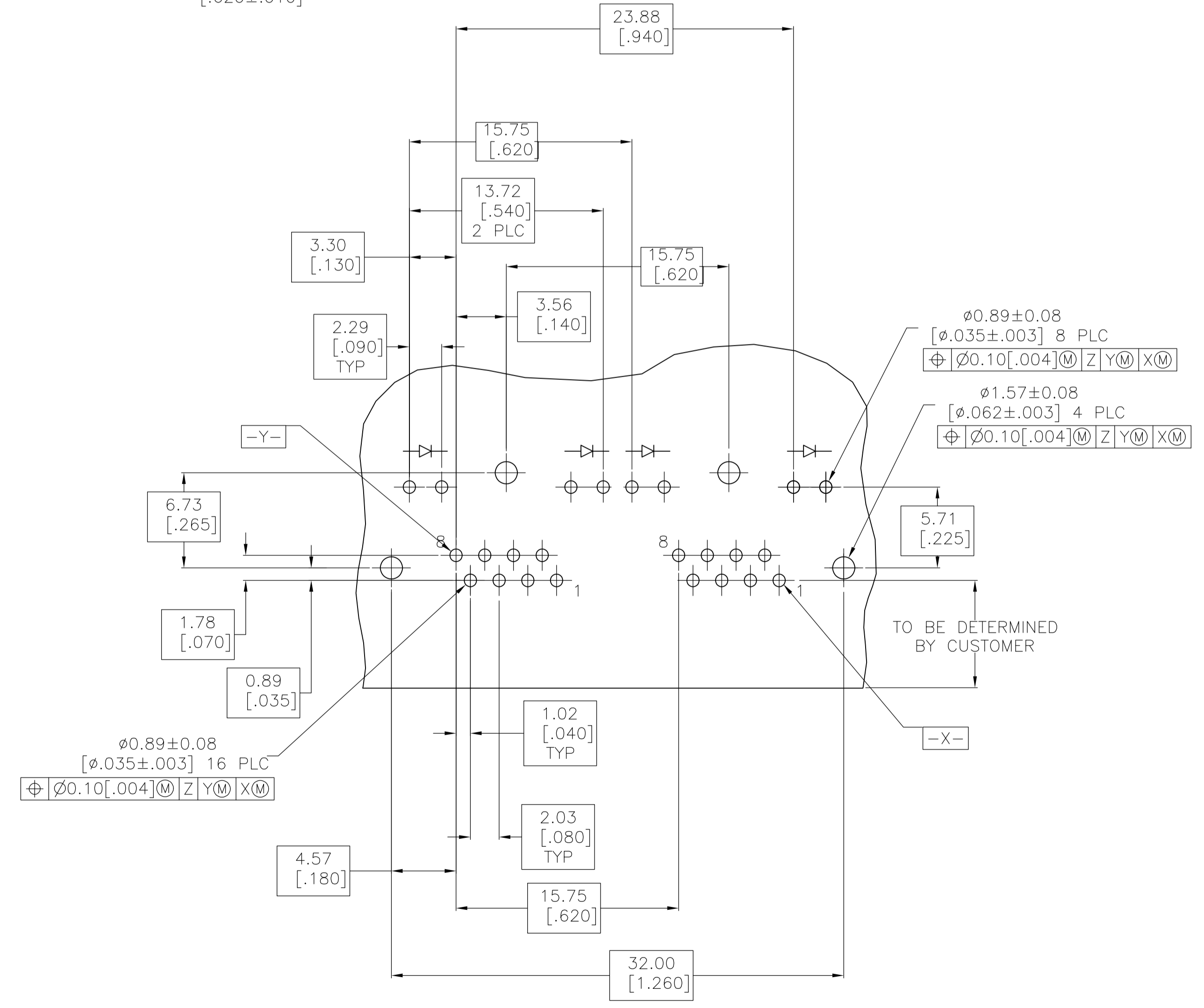


- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK, UL94V-0  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MIN THICK NICKEL.  
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MIN SATIN NICKEL WITH 2.03µm[.000080] MIN TIN POST DIPPED ON PCB GROUND TABS  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- $\triangle$  SUGGESTED PANEL OPENING DIMENSIONS.  
 $\triangle$  SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.  
 $\triangle$  SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE

GREEN	GREEN	1364173-5
YELLOW	GREEN	1364173-1
POSITION 2	POSITION 1	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN M.MORRIS	OBJAN00	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK D.DIXON	OBJAN00	NAME INVERTED MODULAR JACK ASSEMBLY, 1X2, PANEL GROUND, SHIELDED, NO MOUNTING LEGS, WITH LEDS	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± 0.25[.01] 3 PLC ± 0.13[.005] 4 PLC ± - ANGLES ± -		APVD D.DIXON	OBJAN00	PRODUCT SPEC 108-1163-4	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1	WEIGHT -	SIZE A1	SCALE 4:1
		CUSTOMER DRAWING		DRAWING NO 114-2154	
				SHEET 1 OF 1	
				REV C	

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